



SMD Auto X8G HT150C Flex, Ceramic, 0.027 uF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade, 2220, 3.5 mm



General Information		
Series	SMD Auto X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade	
Features	High Temperature, Ultra-Stable, Automotive Grade	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
Qualifications	AEC-Q200	
AEC-Q200	Yes	
Typical Component Weight	130 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	2220
L	5.9mm +/-0.75mm
W	5mm +/-0.4mm
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm

**	3Hill 1/ 0.4Hill	
Т	1mm +/-0.15mm	
S	3.5mm MIN	
В	0.7mm +/-0.35mm	
Packaging Specifications		

Packaging

Specifications		
Capacitance	0.027 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	5%	
Voltage DC	200 VDC	
Dielectric Withstanding Voltage	500 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	37.037 GOhms	

	1000	11	
Packaging Quantity		Dissipation Factor	C
		Aging Rate	C T

T&R, 180mm, Plastic Tape

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